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# IMPORTANT NOTICE

10 December 2015

## 1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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Thank you for your cooperation and understanding,

WeEn Semiconductors



# DATA SHEET

**BTA216 series B**  
Three quadrant triacs  
high commutation

Product specification

October 1997



# Three quadrant triacs high commutation

# BTA216 series B

## GENERAL DESCRIPTION

Glass passivated high commutation triacs in a plastic envelope intended for use in circuits where high static and dynamic  $dV/dt$  and high  $dI/dt$  can occur. These devices will commutate the full rated rms current at the maximum rated junction temperature, without the aid of a snubber.

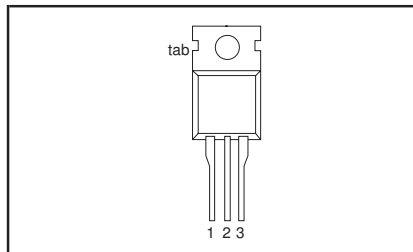
## QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
$V_{DRM}$	<b>BTA216-</b> Repetitive peak off-state voltages	<b>500B</b> 500	<b>600B</b> 600	<b>800B</b> 800	V
$I_{T(RMS)}$	RMS on-state current	16	16	16	A
$I_{TSM}$	Non-repetitive peak on-state current	140	140	140	A

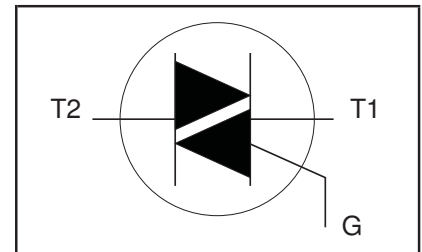
## PINNING - TO220AB

PIN	DESCRIPTION
1	main terminal 1
2	main terminal 2
3	gate
tab	main terminal 2

## PIN CONFIGURATION



## SYMBOL



## LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
				-500 500 <sup>1</sup>	-600 600 <sup>1</sup>	-800 800	
$V_{DRM}$	Repetitive peak off-state voltages		-				V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 99\text{ }^\circ\text{C}$	-	16			A
$I_{TSM}$	Non-repetitive peak on-state current	full sine wave; $T_j = 25\text{ }^\circ\text{C}$ prior to surge	-	140			A
$I^2t$	$I^2t$ for fusing	$t = 20\text{ ms}$	-	150			A
$dI_T/dt$	Repetitive rate of rise of on-state current after triggering	$t = 16.7\text{ ms}$	-	98			$A^2s$
$I_{GM}$	Peak gate current	$I_{TM} = 20\text{ A}; I_G = 0.2\text{ A}; dI_G/dt = 0.2\text{ A}/\mu s$	-	100			$A/\mu s$
$V_{GM}$	Peak gate voltage		-	2			A
$P_{GM}$	Peak gate power		-	5			V
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	5			W
$T_{stg}$	Storage temperature		-40	0.5			W
$T_j$	Operating junction temperature		-	150			$^\circ\text{C}$
				125			$^\circ\text{C}$

<sup>1</sup> Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 A/ $\mu s$ .



## Three quadrant triacs high commutation

## BTA216 series B

### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base	full cycle	-	-	1.2	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	half cycle in free air	-	60	1.7	K/W
			-		-	K/W

### STATIC CHARACTERISTICS

$T_j = 25\text{ °C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{GT}$	Gate trigger current <sup>2</sup>	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$				
		T2+ G+	2	18	50	mA
		T2+ G-	2	21	50	mA
		T2- G-	2	34	50	mA
$I_L$	Latching current	$V_D = 12\text{ V}$ ; $I_{GT} = 0.1\text{ A}$				
		T2+ G+	-	31	60	mA
		T2+ G-	-	34	90	mA
		T2- G-	-	30	60	mA
$I_H$	Holding current	$V_D = 12\text{ V}$ ; $I_{GT} = 0.1\text{ A}$	-	31	60	mA
$V_T$	On-state voltage	$I_T = 20\text{ A}$	-	1.2	1.5	V
$V_{GT}$	Gate trigger voltage	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$	-	0.7	1.5	V
$I_D$	Off-state leakage current	$V_D = 400\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 125\text{ °C}$ $V_D = V_{DRM(max)}$ ; $T_j = 125\text{ °C}$	0.25	0.4	-	V
			-	0.1	0.5	mA

### DYNAMIC CHARACTERISTICS

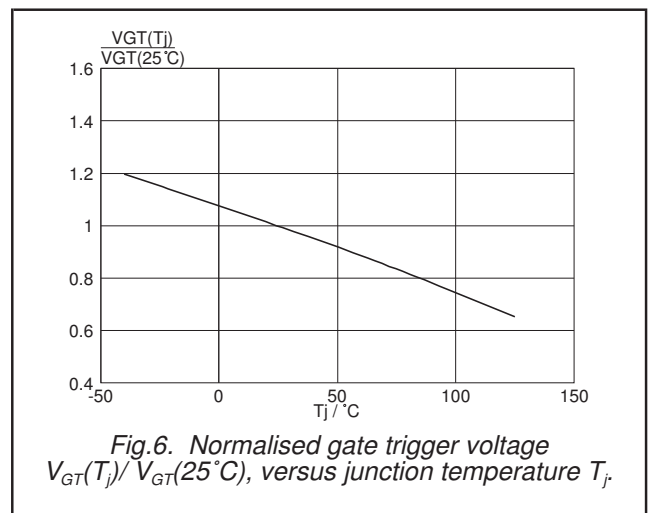
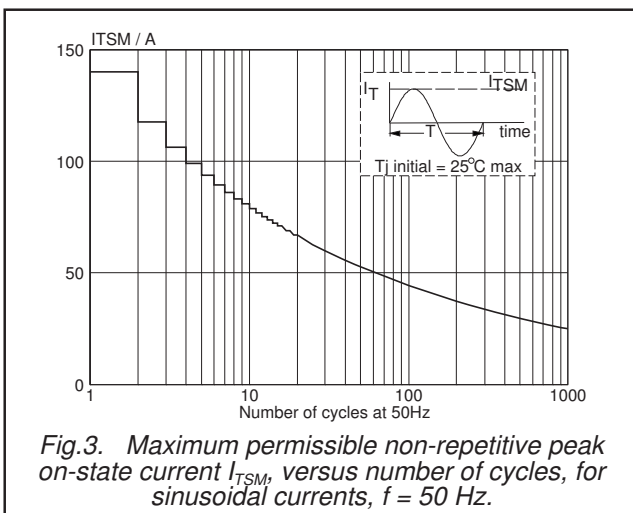
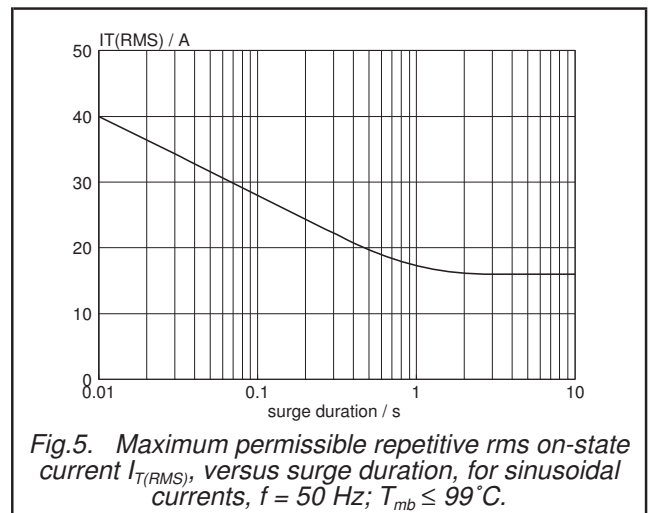
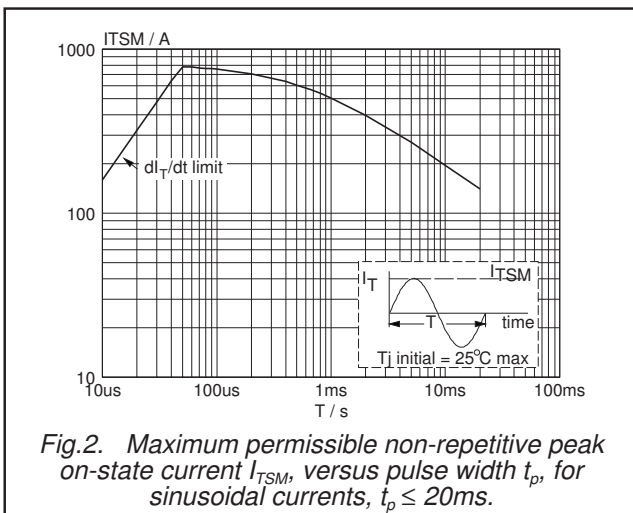
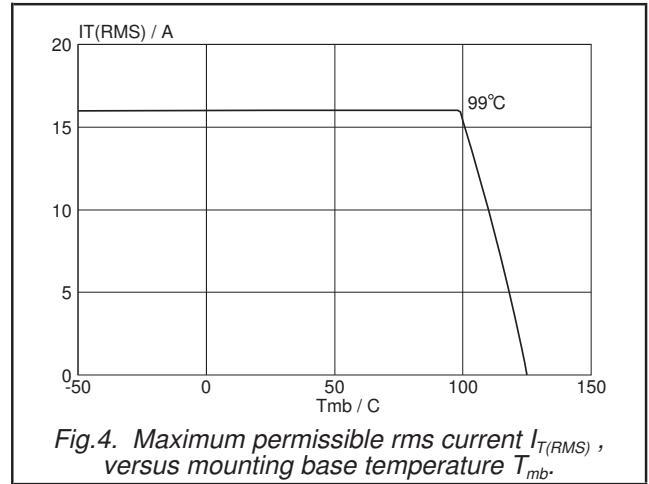
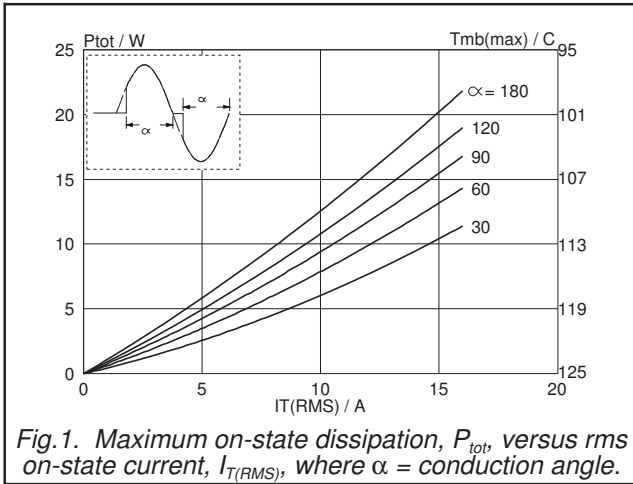
$T_j = 25\text{ °C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$dV_D/dt$	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}$ ; $T_j = 125\text{ °C}$ ; exponential waveform; gate open circuit	1000	4000	-	V/ $\mu$ s
$dI_{com}/dt$	Critical rate of change of commutating current	$V_{DM} = 400\text{ V}$ ; $T_j = 125\text{ °C}$ ; $I_{T(RMS)} = 16\text{ A}$ ; without snubber; gate open circuit	-	28	-	A/ms
$t_{gt}$	Gate controlled turn-on time	$I_{TM} = 20\text{ A}$ ; $V_D = V_{DRM(max)}$ ; $I_G = 0.1\text{ A}$ ; $dI_G/dt = 5\text{ A}/\mu$ s	-	2	-	$\mu$ s

<sup>2</sup> Device does not trigger in the T2-, G+ quadrant.

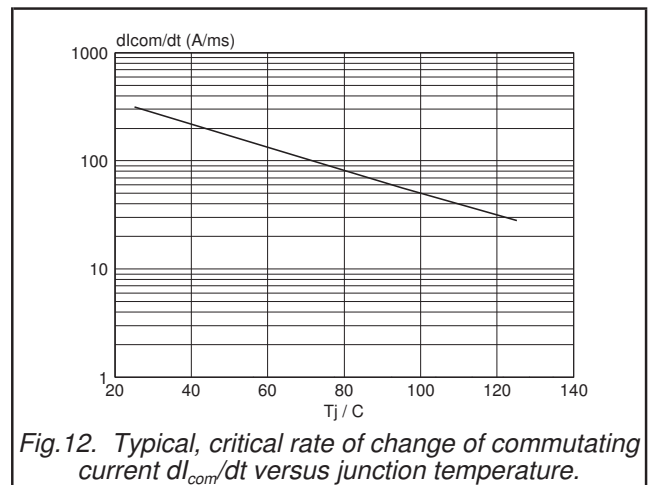
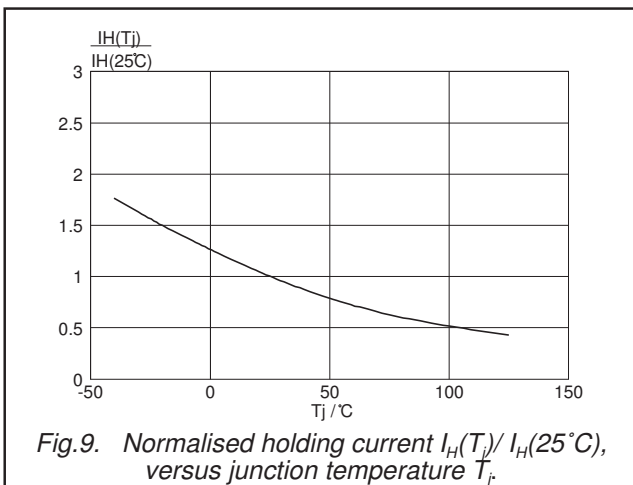
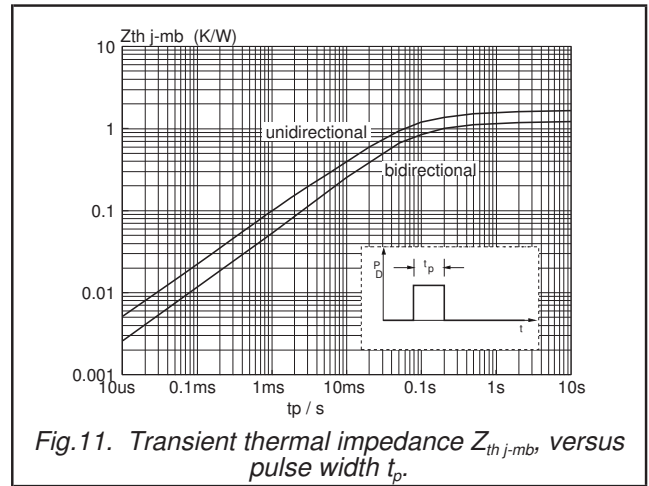
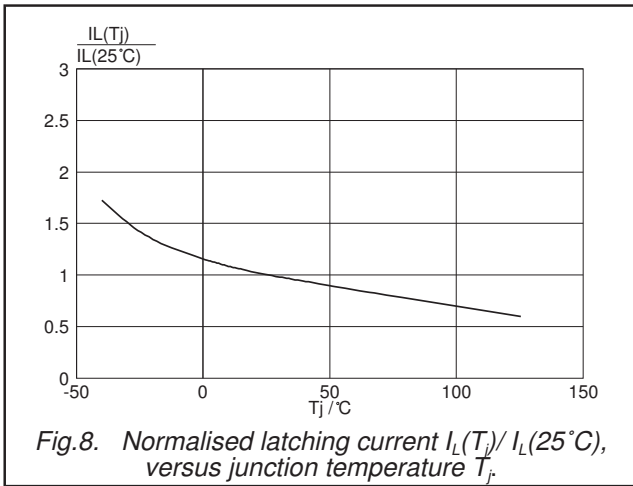
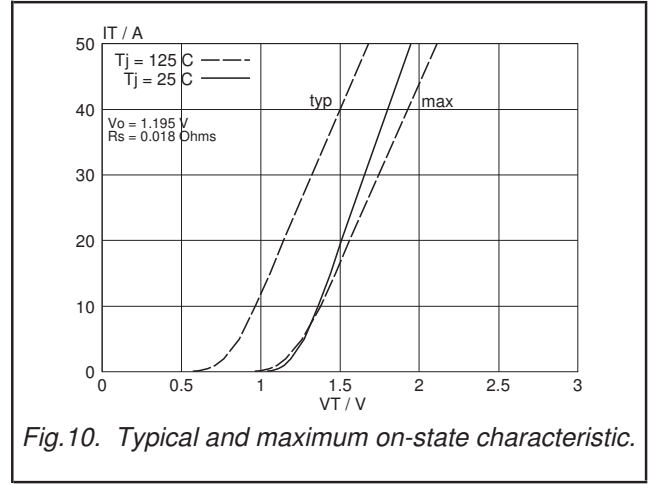
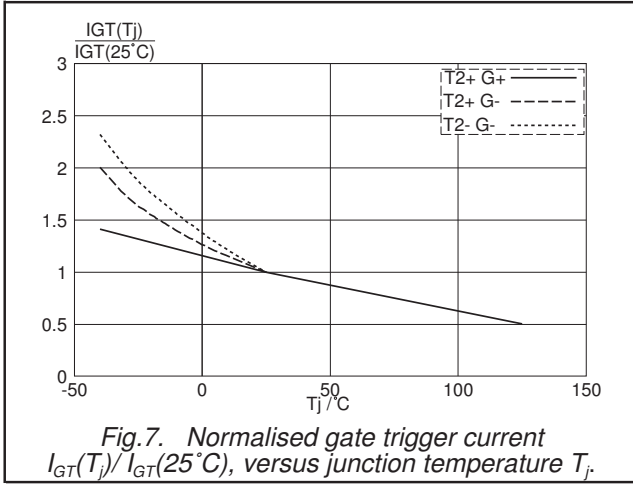
Three quadrant triacs  
high commutation

BTA216 series B



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**MECHANICAL DATA**

Dimensions in mm

Net Mass: 2 g

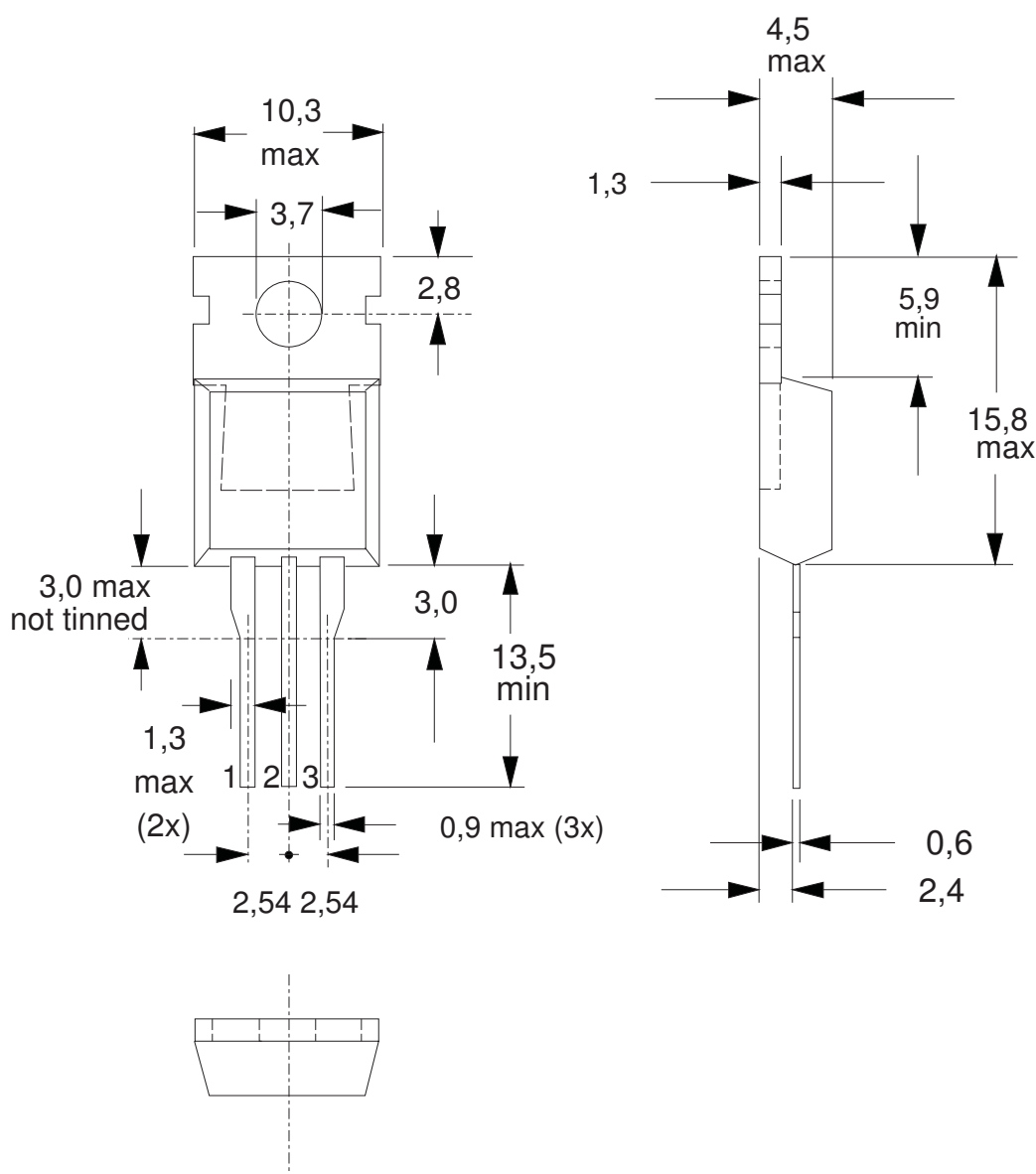


Fig. 13. TO220AB; pin 2 connected to mounting base.

**Notes**

1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".



## Legal information

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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